

DICING TAPE

5

ABSTRACT OF THE DISCLOSURE

Dicing tape comprises a tackifiable adhesive layer which is composed mainly of a polyimide and has a peel strength of 0.02 N/mm (20 gf/cm) or greater as the adhesive strength at near room temperature (20-50°C) and a cured peel strength of 0.3 N/mm (300 gf/cm) or greater. The tape exhibits adhesive strength with silicon wafers sufficiently high to allow dicing at near room temperature, and also exhibits high adhesive strength with circuit boards after curing, in light of the processing disadvantages of polyimide-based dicing tape resulting from its low tacky strength (initial adhesive strength) at low temperatures of around room temperature, which requires a higher ambient temperature to increase the adhesive force and thus necessitates supplementary heating equipment.